



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-03-18
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	2K07*UF75JC5	A	SH1A	2013-03-18
Amount	UoM	Unit type	ST ECOPACK Grade	
77.40	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Palladium (Ni/Pd) Tin (Sn), Semi-ma	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	2K07*UF5JC5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	4.403	mg	supplier	die	Silicon (Si)	7440-21-3		4.258	mg	967068	55013
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.035	mg	7949	452
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.013	mg	2953	168
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.06	mg	13627	775
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.025	mg	5678	323
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.011	mg	2498	142
die (s)				supplier	passivation	Alcoxyilane	proprietary		0.001	mg	227	13
Leadframe	Copper & its alloys	32.348	mg	supplier	alloy	Copper (Cu)	7440-50-8		32.259	mg	997249	416783
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.015	mg	464	194
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.027	mg	835	349
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1360	568
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	31	13
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	31	13
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	31	13
Die attach	Other Organic Materials	1.277	mg	supplier	glue	Silver (Ag)	7440-22-4		1.162	mg	909945	15013
Die attach				supplier	glue	acrylate	Proprietary		0.064	mg	50117	827
Die attach				supplier	glue	Methacrylate	Proprietary		0.051	mg	39937	659
Bonding wire	Other inorganic materials	0.054		supplier	wire	Copper (Cu)	7440-50-8		0.054	mg	1000000	698
encapsulation	Other Organic Materials	39.318	mg	supplier	mold compound	Epoxy Resin	Proprietary		2.949	mg	75004	38101
encapsulation	Other Organic Materials			supplier	mold compound	Phenol Resin	Proprietary		1.966	mg	50003	25401
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		34.049	mg	865990	439910
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.197	mg	5010	2545
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.157	mg	3993	2028